

ABSTRACT OF THE DISCLOSURE

An electronic apparatus of the present invention comprises an electronic circuit board; an electrically conductive casing for encasing the electronic circuit board; a semiconductor element module electrically connected to the electronic circuit board; and a resin fixture intervening between the electrically conductive casing and the semiconductor element module, the resin fixture mounted with the semiconductor element module and fitted to the electrically conductive casing. As a result, the resin fixture can suppress a transfer of heat generated in the electronic circuit board to the semiconductor element module.